



Product Change Notification: DSN0-03YRGH168

Date:

07-Sep-2026

Product Category:

8-Bit Microcontrollers, Capacitive Touch Sensors, Memory

Notification Subject:

CCB 8447 Initial Notice: Qualification of G630AY as an additional molding compound material for selected 93LC46x, 93AA46x, 93C46x, 93LC56x, 93AA56x, 93C56x, 93LC66x, 93AA66x, 93C66x, 93LC76x, 93AA76x, 93C76x, 93LC86x, 93AA86x, 93C86x, 25LC010A, 25AA010A, PIC10F20x, 25LC020A, 25AA02xx, 25LC040A, 25AA040A, PIC10F22x, MTCH101, 24VL025, 24LC025, 24AA025xx, 24VL014, 24LC014, 24AA014, 24C01C, 34VL02, 34LC02 and 34AA02 device families available in 6L (SOT-23) package at MMT assembly site.

Affected CPNs:

[DSNO-03YRGH168_Affected_CPN_09072026.pdf](#)

[DSNO-03YRGH168_Affected_CPN_09072026.csv](#)

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of G630AY as an additional molding compound material for selected 93LC46x, 93AA46x, 93C46x, 93LC56x, 93AA56x, 93C56x, 93LC66x, 93AA66x, 93C66x, 93LC76x, 93AA76x, 93C76x, 93LC86x, 93AA86x, 93C86x, 25LC010A, 25AA010A, PIC10F20x, 25LC020A, 25AA02xx, 25LC040A, 25AA040A, PIC10F22x, MTCH101, 24VL025, 24LC025, 24AA025xx, 24VL014, 24LC014, 24AA014, 24C01C, 34VL02, 34LC02 and 34AA02 device families available in 6L (SOT-23) package at MMT assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change(Yes/No)
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Assembly Site	Microchip Technology Thailand (Branch) (MMT)	Microchip Technology Thailand (Branch) (MMT)	No
Wire Material	CuPdAu	CuPdAu	No
Die Attach Material	8006NS	8006NS	No
Molding Compound Material	G600V	G600V G630AY	Yes
Lead-Frame Material	CDA194	CDA194	No
DAP Surface Prep	Ag-RT	Ag	Yes

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying G630AY as additional molding compound material at MMT assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: October 2026

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	September 2026					October 2026			
Work Week	36	37	38	39	40	41	42	43	44
Initial PCN Issue Date		x							
Qual Report Availability						x			
Final PCN Issue Date						x			

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: September 07, 2026: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_DSNO-03YRGH168_Qual_Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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